Registration Is Open!

The premier international packaging, components, and microelectronics systems technology conference

ECTC is the only event that offers an outstanding array of packaging technology information and four full days of engaging seminars. The over 350 technical papers cover advanced packaging technologies such as wafer-level and fan-out packaging, 2.5D, 3D and heterogeneous integration, interposers, advanced substrate, assembly, materials modeling, reliability, interconnections, packaging for high speed and high bandwidth, photonics, quantum electronics, flexible and printed electronics.

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Registration Patron: Zymet

The 2024 Program Includes:

- 41 Technical sessions with a total number of 350+ technical papers including:
  - 5 Interactive Session including one student session
- 9 Special invited sessions plus a diversity panel and a Young Professionals event
- 16 CEU-approved Professional Development Courses

With multiple opportunities for networking and a Technology Corner Exhibit that showcases industry-leading product and service companies from around the world, the ECTC is where you belong. Welcome back to the in-person conference format.

To learn more about the conference go to the ECTC website and join the ECTC LinkedIn group to receive the latest updates on the most important topics in microelectronic packaging.

Technical Program

Special Sessions and Panels

IEEE EPS President's Panel
Challenges in Education and Workforce Development in the New Chips Economy

Session Chairs:
Pat Thompson (*TI, IEEE EPS President*), K. Pearsall (*Boss Precision*)

2023 ECTC Plenary Session
The Future of Semiconductor Industry. Emerging Start-ups and Technologies for Advanced Packaging

Session Chairs:
Rozalia Beica, Simarpreet Rattan (*Microsoft*), Farhang Yazdani (*Broadpak*)

Session Sponsor: AT&S

ECTC/iTherm Diversity Panel

Session Chairs:
Vidya Jayaram (*Intel*) for ECTC, Christina Amon (*U. of Toronto*) for iTherm

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IEEE EPS Seminar
Challenges of Chiplets on Large Substrates

Session Chairs:
Takashi Hisada (*Rapidus*) and Yasumitsu Orii (*Rapidus*)

Session Sponsor: Binghamton University

ECTC Special Session
Exploring the Impact of Industry-Government Co-Investments for the Advanced Electronics Sector in North America, Asia and Europe

Session Chair:
Przemyslaw Gromala (*Bosch*); Erik Jung (*Fraunhofer IZM*)

ECTC Special Session
Challenges and Opportunities in Advancing Metrology for Next-Generation Microelectronics

Session Chair:
Ran Tao (*NIST*); Benson Chan (*Binghamton University*)

ECTC Special Session
Efficient and Innovative Thermal Management for Power Hungry AI/ML Applications: Challenges and Opportunities

Session Chair:
Zhi Yang (*Groq*); Sevket Yuruker (*Tesla*)

ECTC Special Session
RF Packaging for Communication and Sensing Applications above 100 GHz – Technologies, Design Challenges and Emerging Solutions

Session Chair:
Maciej Wojnowski (*Infineon Technologies AG*), Ivan Ndip (*Fraunhofer IZM*)

ECTC Young Professionals Network Panel

Session Chairs:
Aakrati Jain (*IBM*)

Professional Development Courses

PDC Chairs:
Kitty Pearsall (*Boss Precision*), Jeff Suhling (*Auburn University*)

1. High-Reliability Soldering in Semiconductor Packaging
Course Leader: Ning-Cheng Lee – ShinePure Hi-Tech

2. Photonic Technologies for Communication, Sensing, and Displays
Course Leader: Torsten Wipiejewski, Huawei Technologies

3. From Wafer to Panel Level Packaging
Course Leaders: Tanja Braun and Piotr Mackowiak – Fraunhofer IZM

4. Eliminating Failure Mechanisms in Advanced Packages
Course Leader: Darvin Edwards – Edwards Enterprises

5. **Navigating Thermal and Reliability Challenges in Chip Components for Automotive High-Performance Compute Systems**

Course Leader: Fen Chen -- Automotive Reliability/Validation Consultation Services

6. **Polymers for Advanced Packaging**

Course Leader: Jeffrey Gotro –InnoCentrix, LLC

7. **Flip Chip Technologies**

Course Leader: Shengmin Wen – HaiSemi, Inc.

8. **Reliable Integrated Thermal Packaging for Power Electronics**

Course Leader: Patrick McCluskey – University of Maryland

9. **Additive Flexible Hybrid Electronics – Manufacturing and Reliability**

Course Leader: Pradeep Lall – Auburn University

10. **Fundamentals of RF Design and Fabrication Processes of Fan-Out Wafer/Panel Level and Advanced RF Packages**

Course Leaders: Ivan Ndip – Fraunhofer IZM/Brandenburg University of Technology and Markus Wöhrmann – Fraunhofer IZM

11. **Advanced Packaging – Fan-Out, Chiplet, and Heterogeneous Integration**

Course Leader: John Lau – Unimicron

12. **Analysis of Fracture and Delamination in Microelectronic Packages**

Course Leader: Andrew Tay - National University of Singapore

13. **Advanced Packaging for MEMS and Sensors**

Course Leader: Horst Theuss – Infineon Technologies AG

14. **Nano Materials and Polymer Composites for Electronic Packaging**

Course Leaders: C.P. Wong – Georgia Tech and Daniel Lu – Henkel Corporation

15. **Design-On-Simulation for Advanced Packaging Reliability and Life Prediction**

Course Leaders: Kuo-Ning Chiang – National Tsing Hua University and Xuejun Fan – Lamar University

16. **Thermal Spreading and Contact Resistance**

Course Leaders: Yuri Muzychka – Memorial

University of Newfoundland and Marc Hodes – Tufts University

Come to ECTC and Visit Over 120 Exhibitors

The ECTC Exhibition is pleased to showcase over 120 companies and organizations representing the full spectrum of materials, services, equipment, and products for the electronic packaging industry. Complementing the strength of the ECTC technical program, the Exhibition provides an unparalleled opportunity for engineers and decision-makers to discuss and collaborate with representatives from leading electronic packaging companies.

Remaining exhibit space is extremely limited. For more information contact Sam Karikalan ECTC Exhibits Chair.

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Saturday - Sunday
9am - 5pm local time

For more information on the 2024 ECTC visit www.ectc.net.

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